

IN THE CLAIMS:

1. (Canceled)

2. (Currently Amended) The replicate of claim + 35 wherein said integrated circuit includes a clock and a non-volatile memory, whereby a time associated with each event can be recorded in said memory for retrieval at a later point in time.

3. (Currently Amended) The replicate of claim + 35 wherein said power supply is integral with said integrated circuit.

4. (Currently Amended) The replicate of claim + 35 wherein said integrated circuit and said traces are printed on said backing sheet.

5. (Currently Amended) The replicate of claim + 35 wherein an adhesive is applied to said backing sheet for attachment of said replicate to said blister package.

6. (Currently Amended) The replicate of claim + 35 wherein a cover sheet is applied to said replicate with said integrated circuit and said conductive traces sandwiched between said cover sheet and said backing sheet to create a laminated replicate.

Claims 7-11. (Canceled)

12.(Currently Amended) The package of claim ~~11~~ 37 including a cover sheet through which said blisters project, said cover sheet being applied to said one surface of said backing material so as to capture said replicate between itself and said one surface of said backing material.

Claims 13-25. (Canceled)

26. (Currently Amended) The package of claim ~~25~~ 38 wherein said integrated circuit is provided on said backing sheet.

27.(Currently Amended) The package of claim ~~25~~ 38 wherein said integrated circuit is provided on said first flap.

Claims 28-34. (Canceled)

35. (New) A replicate for application to a blister package containing a plurality of articles, each in an individual blister such that each such article can be projected through a corresponding portion of the package and the replicate for removal from the package, said replicate including a frangible backing sheet, an integrated circuit on said backing sheet, a power source for the integrated circuit, means for attaching said replicate to said package, and a plurality of individual electrically conductive traces on said backing sheet, said traces defining a grid pattern of intersecting sets of parallel such traces, said traces being positioned on said backing sheet so that more than one thereof will intersect each of said blisters when said replicate is

attached to said package, said intersecting sets of traces being connected to said integrated circuit, whereby when an article is projected from its blister through said replicate the corresponding traces are broken, so as to define an event that can be recorded by said integrated circuit.

36. (New) A blister package comprising:

a sheet of material having a plurality of openings therethrough.

a plurality of individual flexible blisters mounted to one surface of said sheet, each of said blisters being in registry with a corresponding opening;

an article located in each of said blisters;

a closure seal formed of frangible material extending across each said opening so as to hermetically capture the article in the corresponding blister;

a replicate secured to the opposite surface of said sheet, said replicate including:

a frangible backing sheet;

an integrated circuit on said backing sheet;

a power source for the integrated circuit;

means for attaching said replicate to said opposite surface; and

a plurality of individual electrically conductive traces on said backing sheet, said traces defining a grid pattern of intersecting sets of parallel such traces;

said intersecting sets of traces being positioned on said backing sheet so that more than one thereof will intersect a corresponding one of said closure seals when said replicate is attached to said package, said intersecting sets of traces being connected to said integrated circuit, whereby when an article is projected from its blister through said closure seal and said replicate the corresponding traces are broken, so as to define an event that can be recorded by said integrated circuit.

37. (New). A blister package comprising:

- a sheet of material having a plurality of openings therethrough.
- a plurality of individual flexible blisters mounted to one surface of said sheet, each of said blisters being in registry with a corresponding opening;
- an article located in each of said blisters;
- a closure seal formed of frangible material extending across each said opening so as to hermetically capture the article in the corresponding blister;
- a replicate secured to said one surface of said sheet, said replicate including:
 - a frangible backing sheet;
 - an integrated circuit on said backing sheet;
 - a power source for the integrated circuit;
 - means for attaching said replicate to said one surface; and
 - a plurality of individual electrically conductive traces on said backing sheet, said traces defining a grid pattern of intersecting sets of parallel such traces;
- said sets of intersecting traces being positioned on said backing sheet so that more than one thereof will intersect a corresponding one of said blisters when said replicate is attached to said package, said intersecting sets of traces being connected to said integrated circuit, whereby when an article is projected from its blister through said closure seal and said replicate the corresponding traces are broken, so as to define an event that can be recorded by said integrated circuit.

38. (New) A blister package comprising:

a first flap, a second flap, and a spine hingedly attached to each of said first and second flaps;

a plurality of individual flexible blisters mounted to an inside surface of said second flap;

a plurality of openings extending through a rear surface of said second flap, each of said openings being in registry with a corresponding blister;

an article located in each of said blisters;

a closure seal formed of frangible material extending across each said opening so as to hermetically capture the article in the corresponding blister;

a replicate secured to said inside surface of said second flap, said replicate including:

a frangible backing sheet;

an integrated circuit;

a power source for the integrated circuit;

means for attaching said replicate to said second flap; and

a plurality of individual electrically conductive traces on said backing sheet, said traces defining a grid pattern of intersecting sets of parallel such traces;

said sets of intersecting traces being positioned on said backing sheet so that more than one thereof will intersect a corresponding one of said blisters when said replicate is attached to said second flap, said intersecting sets of traces being connected to said integrated circuit, whereby when an article is projected from its blister through said closure seal and said replicate the corresponding traces are broken, so as to define an event that can be recorded by said integrated circuit.